

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A component of a film-forming device apparatus in which a thin film is formed on a substrate using a film-forming material, the component of the film-forming device apparatus comprising:

 a body having a back face and a top face and a large number of through holes each extending from the back face to the top face formed therein,

 wherein one of the back face and the top face includes a surface on which the thin film is adhered during use, and the through holes provide access from the other one of the back face and the top face to the thin film adhered on the surface, whereby a cleaning solution is permitted to penetrate into a boundary between the surface and the thin film adhered thereon.

2. (Currently Amended) The component of a film-forming device apparatus according to claim 1, wherein the through holes have a diameter smaller than a size of any particle of the film-forming material or a plasma thereof, thereby preventing penetration of any particle of the film-forming material or the plasma thereof into the through holes.

3. (Currently Amended) The component of a film-forming device apparatus according to claim 1 or 2, wherein the through holes are formed in such a manner that they are not perpendicular to the surface of the body of the component.

4. (Currently Amended) The component of a film-forming device apparatus according to claim 1, further comprising a layer consisting of a metal film that is easily soluble in the cleaning solution provided on the surface thereof prior to adherence of the thin film thereon during use.

5. (Withdrawn and Currently Amended) A method for cleaning a component of a film-forming device apparatus comprising the steps of:

preparing a body of the component with through holes that extend therethrough; and

immersing the body of the component into a cleaning solution to remove a film adhered to a surface of the body during use, whereby the cleaning solution enters into the through holes and penetrates a boundary between the surface of the body and the film adhered thereto.

6. (Withdrawn and Currently Amended) The method for cleaning a component of a film-forming device apparatus according to claim 5, wherein the step of preparing the body with the through holes includes forming the through holes to be at an angle to the surface other than 90°.

7. (Withdrawn and Currently Amended) The method for cleaning a component of a film-forming device apparatus according to claim 5, wherein the step of preparing the body with the through holes includes forming the through holes to have a diameter

smaller than a size of any particle of film-forming material used in the film-forming device.

8. (Withdrawn and Currently Amended) The method for cleaning a component of a film-forming device apparatus according to claim 5, further comprising the step of forming a layer consisting of a metal film easily soluble in the cleaning solution on the surface of the body prior to the adherence of the film thereon during use.

9. (Withdrawn and Currently Amended) A component for use in a film-forming device apparatus in which a thin film is formed on a substrate using a film-forming material, the component of the film-forming device apparatus comprising:

means for affecting formation of the thin film on the substrate, the means for affecting formation of the thin film having a surface on which the thin film is also formed during use;

means for allowing penetration of a cleaning solution used to remove the thin film from the surface of the means for affecting formation of the thin film into a boundary between the surface of the means for affecting formation of the thin film and the thin film formed thereon.

10. (Withdrawn and Currently Amended) The component for use in a film-forming device apparatus according to claim 9, wherein the means for affecting formation of the thin film comprises a body having a back face and a top face and the means for

allowing penetration of a cleaning solution includes a plurality of through holes each extending from the back face to the top face of the body.

11. (Withdrawn and Currently Amended) The component for use in a film-forming device apparatus according to claim 10, wherein the through holes have a diameter that inhibits penetration of any particle of the film-forming material or a plasma thereof into the through holes.

12. (Withdrawn and Currently Amended) The component for use in a film-forming device apparatus according to claim 10 or 11, wherein the through holes are formed at an acute angle to the surface of the means for affecting formation of the thin film.

13. (Withdrawn and Currently Amended) The component for use in a film-forming device apparatus according to claim 9, further comprising a layer formed on the surface of the means for affecting formation of the thin film before the thin film is formed thereon during use, the layer consisting of a metal film easily soluble in the cleaning solution used to remove the thin film from the means for affecting formation of the thin film.

14. (Withdrawn and Currently Amended) The method for cleaning a component of a film-forming device apparatus according to claim 8, wherein the step of forming the layer includes forming the layer on the surface of the body by one selected from the group consisting of thermal spraying, vapor deposition, sputtering, plating, lamination and any combination thereof.